



## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	Ι <sub>D</sub> T <sub>A</sub> = +25°C
100V	6.0Ω @ V <sub>GS</sub> = 10V	0.17A

# **Description and Applications**

These N-Channel enhancement mode field effect transistors are produced using DIODES proprietary, high density, uses advanced trench technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. These products are particularly suited for low voltage, low current applications such as:

- Small Servo Motor Control
- Power MOSFET Gate Drivers
- Switching Applications

### Features and Benefits

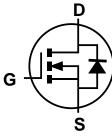
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- High Drain-Source Voltage Rating
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

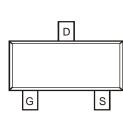
- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)



Top View



Equivalent Circuit



Top View

## Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BSS123-7-F	Commercial	SOT23	3,000 / Tape & Reel
BSS123Q-13	Automotive	SOT23	10,000 / Tape & Reel
BSS123Q-7	Automotive	SOT23	3,000 / Tape & Reel

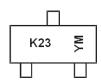
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant

 See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



K23 = Product Type Marking Code YM = Date Code Marking Y or Y $\square$  = Year (ex: C = 2015) M = Month (ex: 9 = September)

#### Date Code Key

Date Code Rey												
Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	Т	U	V	W	Х	Y	Z	А	В	С	D	E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

N-CHANNEL ENHANCEMENT MODE MOSFET



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	100	V
Gate-Source Voltage	Continuous	V <sub>GSS</sub>	±20	V
Continuous Drain Current (Nate 5) V/ 40V/	Continuous	ID	170	~ ^
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	Pulsed	I <sub>DM</sub>	680	mA

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	PD	300	mW
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 5)	R <sub>0JA</sub>	417	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-55 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
		-	-	0.1	μA	$V_{DS} = 100V, V_{GS} = 0V$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	30	μA	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V @ T <sub>A</sub> = 150°C (Note 7)
		-	-	10	nA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage, Forward	I <sub>GSSF</sub>	-	-	50	nA	$V_{GS} = 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)		•				÷
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.8	1.4	2.0	V	$V_{DS} = V_{GS}, I_D = 1mA$
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	-	6.0	Ω	$V_{GS} = 10V, I_D = 0.17A$
Static Drain-Source On-Resistance		-	-	10		$V_{GS} = 4.5V, I_D = 0.17A$
Forward Transfer Admittance	<b>g</b> <sub>FS</sub>	80	370	-	mS	V <sub>DS</sub> =10V, I <sub>D</sub> = 0.17A, f = 1.0KHz
Diode Forward Voltage	V <sub>SD</sub>	-	0.84	1.3	V	$V_{GS} = 0V, I_{S} = 0.34A$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	Ciss	-	22	60		
Output Capacitance	C <sub>oss</sub>	-	3.5	15	pF	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$
Reverse Transfer Capacitance	Crss	-	2.0	6		
SWITCHING CHARACTERISTICS (Note 7)						
Turn-On Delay Time	t <sub>D(ON)</sub>	-	-	8	ns	
Turn-On Rise Time	t <sub>R</sub>	-	-	8	ns	$V_{GS} = 10V, V_{DD} = 30V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	-	-	13	ns	$I_{D} = 0.28A, R_{GEN} = 50\Omega$
Turn-Off Fall Time	t⊧	-	-	16	ns	

5. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com.6. Short duration pulse test used to minimize self-heating effect.7. Guaranteed by design. Not subject to production testing. Notes:



V<sub>GS</sub>=10V

V<sub>GS</sub>=5.0V

 $\begin{array}{ccc} 1 & 2 & 3 & 4 \\ V_{\text{DS}}, \text{DRAIN-SOURCE VOLTAGE} \left( \text{V} \right) \end{array}$ 

Figure 1. Typical Output Characteristic

V<sub>GS</sub>=10V, I<sub>D</sub>=170mA

V<sub>GS</sub>=7.0V

′<sub>GS</sub>=4.0V

V<sub>GS</sub>=3.0V

5

V<sub>GS</sub>=6.0V

0.7

0.6

0.5

0.4

0.3

0.2

0.1

0.0

2.2

2

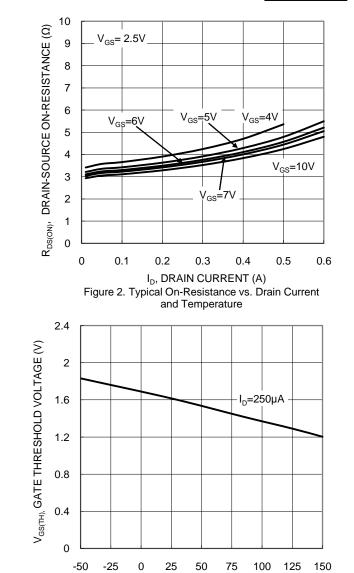
1.8

1.6

1.4

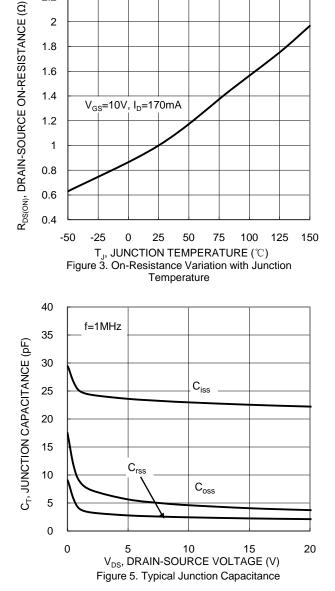
1.2 1 0

I<sub>D</sub>, DRAIN CURRENT (A)



**BSS123** 

T<sub>J</sub>, JUNCTION TEMPERATURE (℃) Figure 4. Gate Threshold Variation vs. Junction Temperature

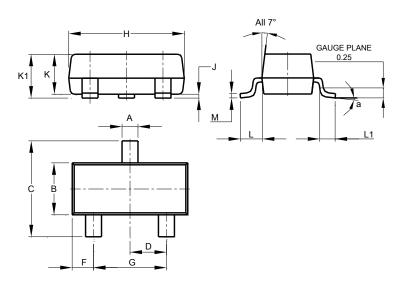




**BSS123** 

# **Package Outline Dimensions**

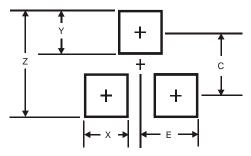
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а		8°					
All	Dimens	ions in	mm				

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
Z	2.9			
Х	0.8			
Y	0.9			
С	2.0			
E	1.35			



# **BSS123**

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